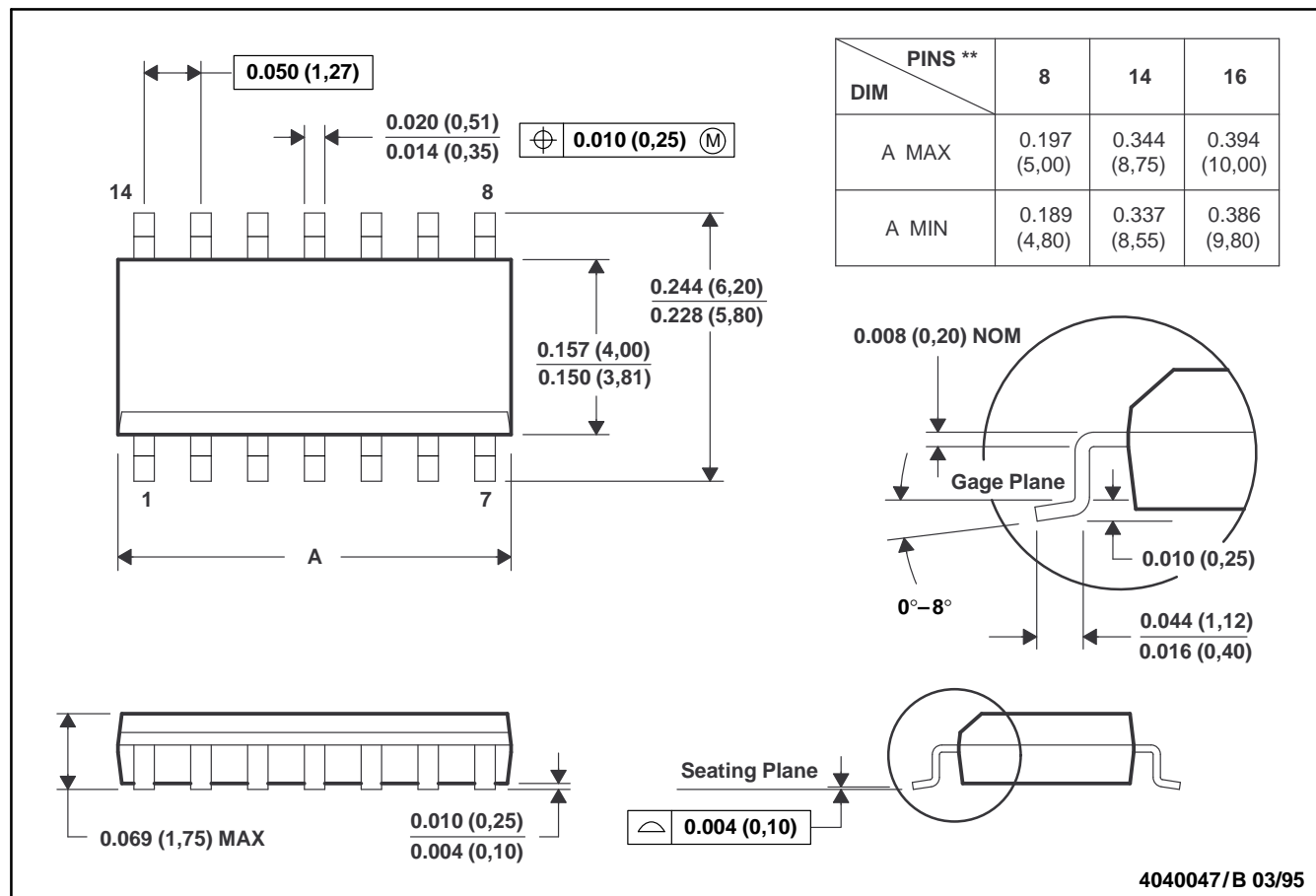


**D (R-PDSO-G\*\*)****PLASTIC SMALL-OUTLINE PACKAGE****14 PIN SHOWN**

- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).  
 D. Four center pins are connected to die mount pad.  
 E. Falls within JEDEC MS-012

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